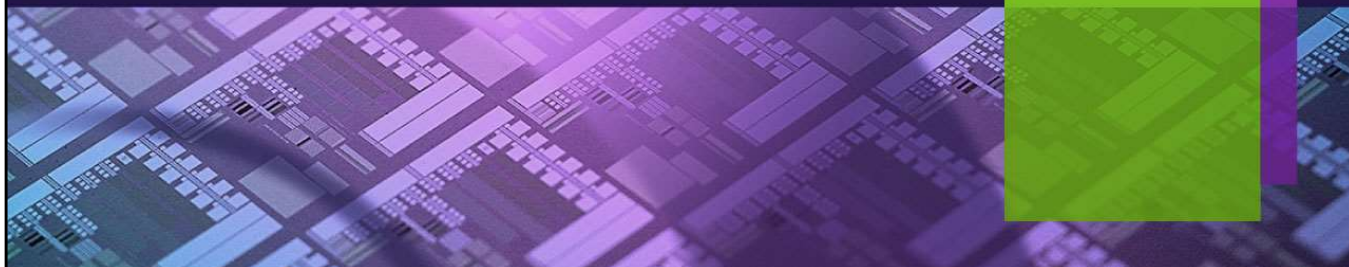


FY2025 (April 2024 - March 2025) Financial Announcement

April 30, 2025

Agenda:

- Consolidated Financial Summary
Hiroshi Kawamoto, SVP & GM, Division Officer of Finance Division
- Business Environment and Financial Estimates
Toshiki Kawai, Representative Director, President & CEO



Forward Looking Statements

- Disclaimer regarding forward-looking statements

Forward-looking statements with respect to TEL's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors, including political and economic situation, semiconductor market conditions, intensification of sales competition, safety and product quality management, intellectual property-related matters and impacts from infectious diseases.

- Processing of numbers

For the amount listed, because fractions are rounded down, there may be the cases where the total for certain account titles does not correspond to the sum of the respective figures for account titles. Percentages are calculated using full amounts, before rounding.

- Foreign exchange risk

In principle, export sales of Tokyo Electron's products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of foreign exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.

FY2025 Consolidated Financial Summary

April 30, 2025

Hiroshi Kawamoto
SVP & GM, Division Officer of Finance Division



Good afternoon. I am Kawamoto of Finance Division.

I would like to present the consolidated financial summary of the fiscal year ended March 2025.

Financial Summary

(Billion yen)

	FY2024	FY2025	FY2025 vs FY2024	(Reference) FY2025 estimates announced on February 6, 2025
Net sales	1,830.5	2,431.5	+32.8%	2,400.0
Gross profit	830.2	1,146.2	+38.1%	1,129.0
Gross profit margin	45.4%	47.1%	+1.7pts	47.0%
SG&A expenses	374.0	448.9	+20.0%	449.0
Operating income	456.2	697.3	+52.8%	680.0
Operating margin	24.9%	28.7%	+3.8pts	28.3%
Income before income taxes	473.4	706.1	+49.1%	691.0
Net income attributable to owners of parent	363.9	544.1	+49.5%	526.0
EPS (Yen)	783.75	1,182.40	+50.9%	1,142.47
R&D expenses	202.8	250.0	+23.2%	254.0
Capital expenditures	121.8	162.1	+33.1%	170.0
Depreciation and amortization	52.3	62.1	+18.7%	63.0

1. In principle, export sales of Tokyo Electron's products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of foreign exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.
2. Profit ratios are calculated using full amounts, before rounding.

Investor Relations / April 30, 2025



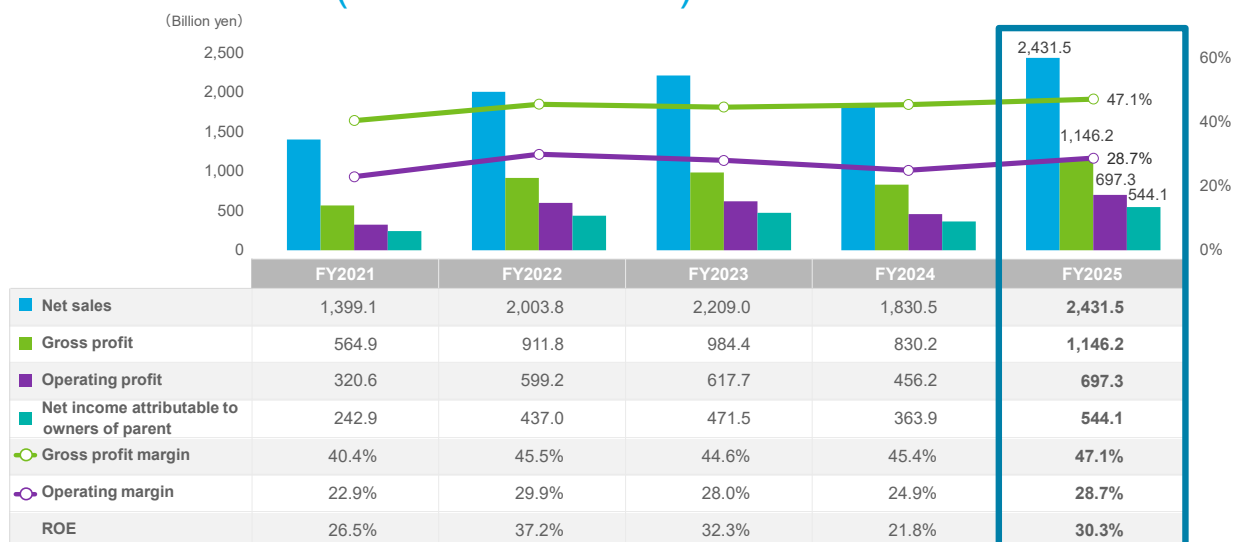
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This slide shows the financial summary of the fiscal year ended March 2025. First of all, I would like to highlight that the results beat our previously announced guidance in net sales, income, and profit margin. Please look mainly at the figures in the blue box.

Driven by the customers' active spendings both for advanced and mature nodes, our net sales reached 2 trillion 431.5 billion yen, 32.8% increase year over year. Gross profit was 1 trillion 146.2 billion yen, exceeding the 1 trillion yen level for the first time. Gross profit margin rose to 47.1%, contributed by high-value added and high-profit-margin products. Operating income was 697.3 billion yen, 52.8% increase year over year. Net income attributable to owners of parent was 544.1 billion yen, 49.5% increase year over year.

R&D expenses were 250.0 billion yen, 23.2% increase from the previous fiscal year since we continued investing for our growth as I said before. Capital expenditures were 162.1 billion yen, mainly due to construction projects in various sites, such as development buildings in Tokyo Electron Kyushu and Tokyo Electron Miyagi, as well as procurement of equipment used for evaluation. Deprecation was 62.1 billion yen, 18.7% increase year over year.

Financial Trend (FY2021~FY2025)



From the beginning of FY2022, the Company applies "Accounting Standard for Revenue Recognition" (ASBJ Statement No. 29).

Net sales, gross profit, operating profit and net income reached record high

Investor Relations / April 30, 2025

TEL

5

This shows financial trend. In the fiscal year ended March 2025, net sales, gross profit, operating income and net income hit all time high. Also, gross profit margin and net profit margin reached record high. ROE was 30.3%.

Financial Summary (Quarterly)

(Billion yen)

	FY2024	FY2025				vs. Q3 FY2025	vs. Q4 FY2024
	Q4	Q1	Q2	Q3	Q4		
Net sales	547.2	555.0	566.5	654.5	655.4	+0.1%	+19.8%
Gross profit	256.1	264.0	259.9	311.7	310.5	-0.4%	+21.3%
Gross profit margin	46.8%	47.6%	45.9%	47.6%	47.4%	-0.2pts	+0.6pts
SG&A expenses	110.8	98.2	111.7	112.1	126.7	+13.1%	+14.3%
Operating income	145.2	165.7	148.1	199.6	183.7	-7.9%	+26.6%
Operating margin	26.5%	29.9%	26.2%	30.5%	28.0%	-2.5pts	+1.5pts
Income before income taxes	157.8	167.2	153.6	200.1	185.1	-7.5%	+17.3%
Net income attributable to owners of parent	124.9	126.1	117.7	157.2	142.9	-9.1%	+14.4%
R&D expenses	58.4	53.4	62.0	61.8	72.7	+17.7%	+24.5%
Capital expenditures	32.9	23.9	53.3	50.2	34.6	-31.1%	+4.9%
Depreciation and amortization	15.3	13.2	14.5	16.0	18.3	+14.4%	+19.7%

1. In principle, export sales of Tokyo Electron's products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of foreign exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.
2. Profit ratios are calculated using full amounts, before rounding.

Investor Relations / April 30, 2025



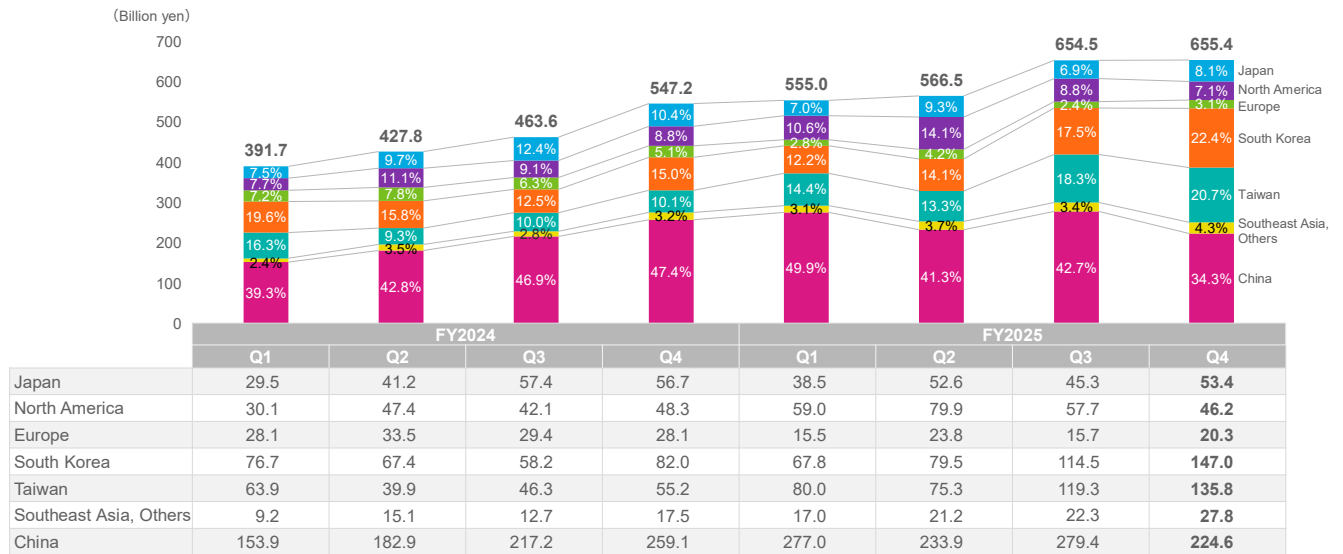
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This slide shows the quarterly financial summary. I will mainly refer to the figures in the blue box.

In the fourth quarter, we generated net sales of 655.4 billion yen, slightly higher than net sales in the third quarter. Gross profit was 310.5 billion yen, 0.4% decline from the previous quarter. Gross profit margin was 47.4%, 0.2 percentage points drop from the previous quarter. Operating income was 183.7 billion yen, 7.9% drop from the previous quarter, due to the increase of SG&A expenses mainly including R&D expenses. Operating profit margin was 28.0%, 2.5-percentage-point decline from the third quarter. Net income attributable to owners of parent was 142.9 billion yen, 9.1% decrease from the previous quarter.

Capital expenditures in the fourth quarter were 34.6 billion yen.

Composition of Net Sales by Region (Q1 FY2024 - Q4 FY2025)

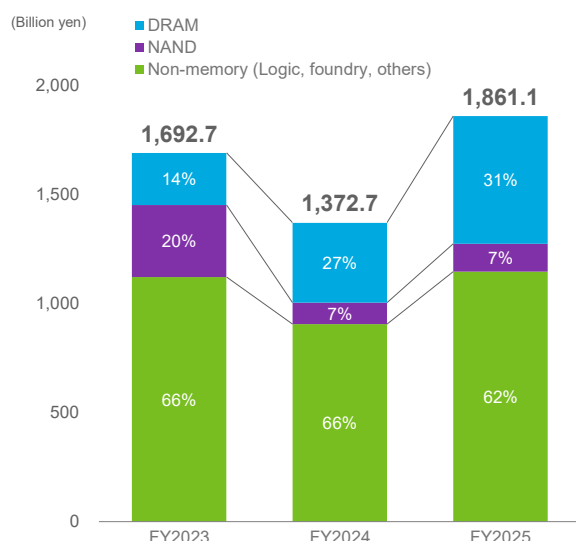


This slide shows net sales by region.

As for the net sales composition in the fourth quarter, proportion of Korea and Taiwan rose by 4.9 and 2.4 percentage points to reach 22.4% and 20.7%, respectively, quarter-over-quarter.

The proportion of sales to China remained above 40% previously, but in the fourth quarter, due to some shipments pulled forward to the third quarter and a peak out of capital investment by emerging customers, the China proportion declined by 8.4 percentage points from the previous quarter to 34.3%.

SPE New Equipment Sales by Application



1. SPE: Semiconductor Production Equipment

2. Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.

Investor Relations / April 30, 2025

TEL

8

- DRAM: Leading-edge investment (HBM etc.) was a significant contributor for higher sales and a larger composition ratio
- Non-volatile memory: Sales were on an upward trajectory despite the composition ratio remaining unchanged as customer investment eased towards a recovery
- Non-memory: Sales rose significantly on active investment in leading-edge nodes as well as demand for mature nodes

This shows SPE new equipment sales by application.

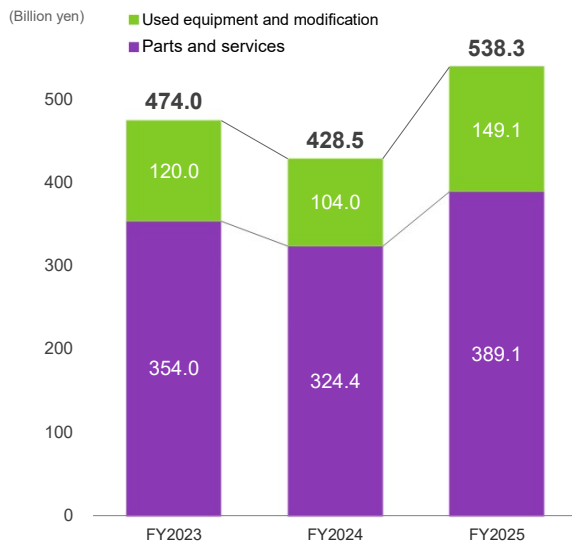
In the fiscal year ended March 2025, from the bottom of this chart, sales to non-memory customers accounted for 62%, non-volatile memory accounted for 7%, and DRAM accounted for 31%.

For DRAM, active investment for advanced technologies such as HBM significantly contributed to the increase of sales to DRAM customers and the rise of its proportion.

The proportion of sales to non-volatile memory customers remained flat year over year, but as customer investment gradually started picking up, our sales showed an increase.

Sales to non-memory customers rose significantly from the previous fiscal year, driven by strong demand for mature nodes as well as active capital investment for advanced nodes.

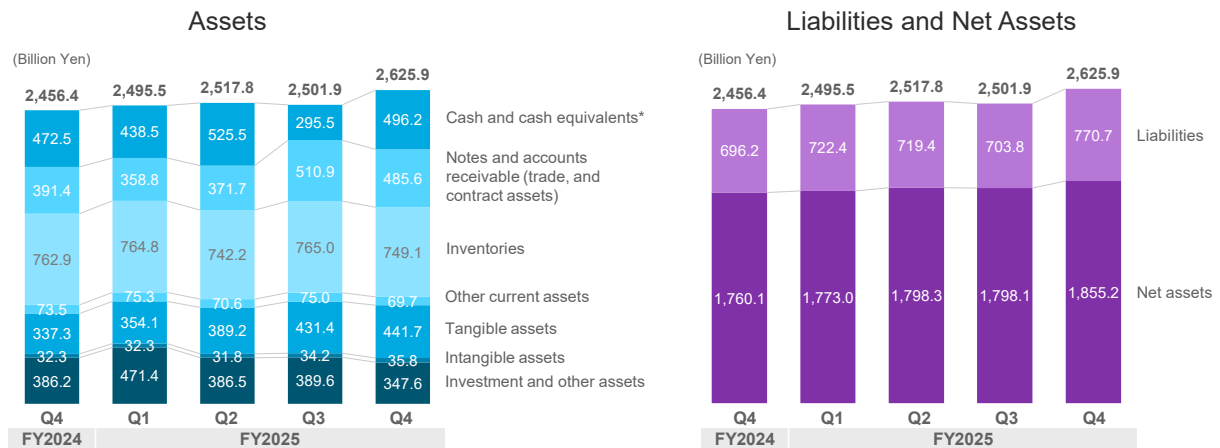
Field Solutions Sales



- Field Solutions sales in FY2025 were 538.3B yen, up 25.6% YoY
- Both parts and services and used equipment and modification sales were in good shape along with the recovery of customers' fab utilization rates

This slide shows the Field Solutions sales. In FY2025, field solution sales were 538.3 billion yen, growing by 25.6% year over year. Along with improving utilization rate of customers fabs, we enjoyed strong sales for parts, services, used equipment, and modifications.

Balance Sheet (Quarterly)



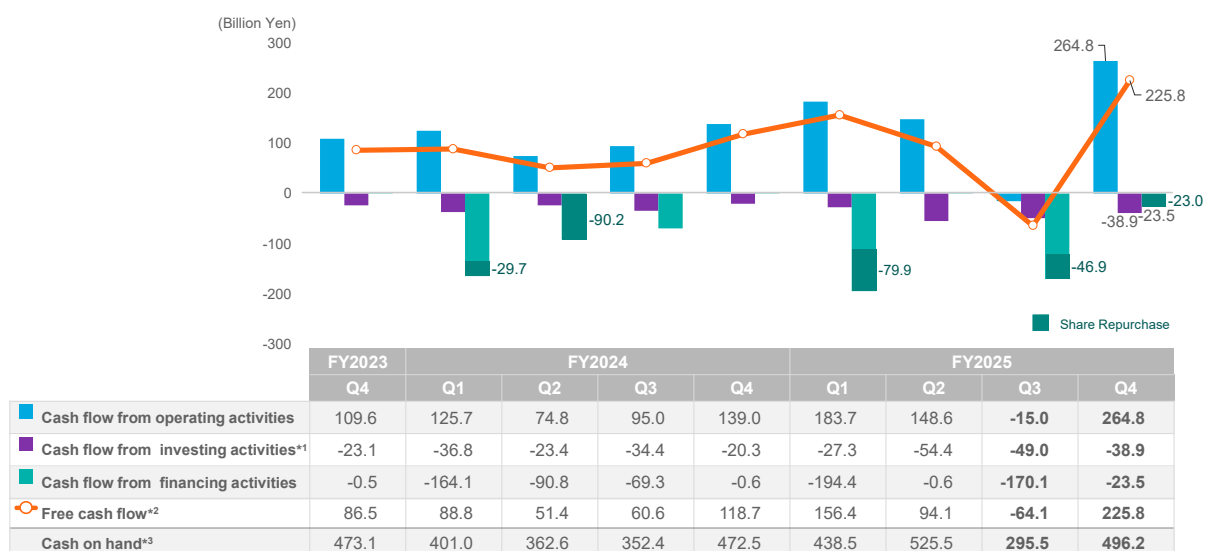
*Cash and cash equivalents: "Cash and deposits" + "Short-term investments", etc. ("Securities" in Balance Sheet).

This slide shows the balance sheet.

Total assets were 2 trillion 625.9 billion yen. Cash and cash equivalents were 496.2 billion yen, increasing by 200.7 billion yen from the previous quarter. Notes and accounts receivable were 485.6 billion yen, declining by 25.2 billion yen from the previous quarter. Inventories were 749.1 billion yen, 15.9 billion yen decline from the previous quarter. Investment and other assets were 347.6 billion yen, declining by 42.0 billion yen from the previous quarter, due to such a factor as the market capitalization decrease.

For the liabilities and net assets shown on the right-hand side, liabilities were 770.7 billion yen, decreasing by 66.9 billion yen from the previous quarter mainly due to posting of income tax payable. Net assets were 1 trillion 855.2 billion yen, rising by 57.0 billion yen quarter over quarter. The equity ratio was 70.1%.

Cash Flow (Quarterly)



*1 Cash flow from investing activities excludes changes in time deposits and short-term investments.

*2 Free cash flow = "Cash flow from operating activities" + "Cash flow from investing activities" (excluding changes in "Time deposits" and "Short-term investments").

*3 Cash on hand includes "Cash and cash equivalents" + "Time deposits and short-term investments" with original maturities of more than three months.

This slide shows the cash flow.

The cash inflow from operating activities in the fourth quarter was 264.8 billion yen.

The cash outflow from investing activities was 38.9 billion yen, due to acquisition of fixed assets mainly including equipment used for evaluation.

The cash outflow from financing activities was 23.5 billion yen, primarily because of share repurchase.

As a result, free cash inflow was 225.8 billion yen. Free cash flow recorded all-time high both on the quarterly and fiscal-year basis.

This concludes my presentation, thank you for your kind attention.

Business Environment and Financial Estimates

April 30, 2025

Toshiki Kawai
Representative Director, President & CEO



This is Kawai. I will present “Business environment and financial estimates”.

FY2025 Business Highlights

- Achieved record highs for both net sales and profit.
Gross profit exceeded 1 trillion yen for the first time
 - Net sales grew +33%. Sales for DRAM grew significantly by +59% with the adoption of a wide range of equipment for HBM*¹
- Market share expanded by winning PORs*² with strategic products
 - **Etch:** DRAM - major monopoly in capacitor etch; NAND - new POR in channel hole etch (cryogenic etch), expansion in slit etch; logic/HBM - adoption in advanced packaging interconnect processes
 - **Wafer bonders:** Significant increase in demand for temporary bonders/debonders for HBM
 - **Probers:** sales rose by leveraging the trend of expanding investments in advanced logic
- Released new products on the expectation that they will support entry into new areas
 - Episode™ 1 single-wafer plasma CVD system; LEXIA™-EX sputtering system; Acrevia™ Gas Cluster Beam system; Ulucus™ LX extreme laser lift off system
- Completed share repurchase of approx. 150 billion yen

*1 HBM: High Bandwidth Memory
*2 POR: Process of Record

Let me start with the FY2025 full-year business highlights.

In FY2025, due to a drastic increase of investment for advanced logic for AI servers and for HBM as well as the pulled-forward investment by Chinese customers, we generated net sales of 2 trillion 431.5 billion yen, gross profit of 1 trillion 146.2 billion yen, operating income of 697.3 billion yen, and net income of 544.1 billion yen on the full-year basis, all of which hit all-time high. Sales growth rate was 33%. In particular, sales to DRAM customers increased by 59% year-over-year as a broad range of our tools were adopted for HBM.

Our market share also increased significantly. For etch systems, in particular, we succeeded in raising our share by 6 percentage points year-over-year, as we won 100% mass-production PORs from the major customers, for the capacitor etching process which is the most difficult process in DRAM production, one customer adopted our cryogenic etching system in NAND channel etching process which contributed to our sales, we won new PORs in NAND slit etching process which drove sales growth, and demand for etch system grew in interconnect process of advanced packaging for logic and HBM. Sales of wafer bonders increased driven by growing demand for HBM, while sales of wafer probers expanded capitalizing on the growing momentum of advanced logic investment. Share of wafer bonders and wafer probers showed a drastic increase. In particular, bonder sales reached about 30 billion yen, growing by three times over the past two years.

To further expand our future profit, we made steady progress in penetrating into new technology domains. Specifically, we released multiple new outstanding products contributing to the semiconductor technology innovation; for example, penetration to untapped segments such as single-wafer plasma CVD and PVD, gas cluster beam system which improves efficiency of leading-edge lithography, and laser-lift-off system to drastically decrease environmental footprint of processing.

In FY2025, we conducted share repurchase of about 150 billion yen in total.

Business Environment (WFE Market Outlook as of April 2025)

■ **CY2025: Forecasting around \$110B, flat YoY**

- Lull in both automotive and power semiconductor investment, and investment by emerging Chinese manufacturers
- Demand for AI servers is driving investment in leading-edge logic and HBM

■ **CY2026: Double-digit growth is expected**

- Expect continued and significant demand for AI servers, as well as an acceleration in investment in 2nm mass production
- Also expect higher semiconductor demand accompanying the increase in on-device AI for PCs and smartphones

Expanding business opportunities for TEL amid progress in technological innovations of both scaling and heterogeneous integration (GAA*¹, BSPDN*², HBM, testing) in order to achieve even higher speed, higher capacity, higher reliability and lower power consumption

*1 GAA (Gate All Around)

*2 BSPDN (Backside Power Delivery Network)

: A transistor structure where the channel is surrounded by the gate

: Structures that arrange power delivery networks on the backside of wafer

Investor Relations / April 30, 2025

TEL

14

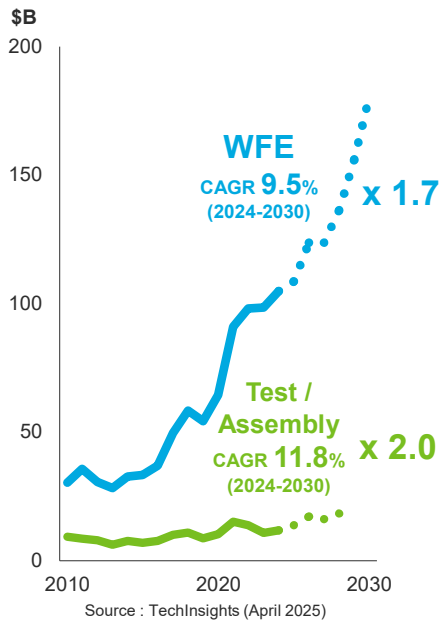
Next, I will talk about the business environment.

As we announced three months ago, we expect CY2025 WFE market size will be about 110 billion dollars, remaining flat year-over-year. Despite a lull in investment to automotive semiconductors and power semiconductors, as well as in mature-node investment by Chinese emerging chipmakers, thanks to continuing expansion of AI semiconductor demand, investment for advanced logic and HBM will be expected. Accordingly, WFE market is expected to keep growing to record-high level.

Also in CY2026, growth of AI-related investment will drive the WFE market. GPU for AI server will shift to the 3 nm node from the current 4 nm node. HBM to be used will evolve from the current 8-chip stacking to 12- and 16-chip stacking while proceeding with device scaling. In addition, full-swing introduction of AI to the edge, such as smartphone and PC, will start, which will trigger demand growth for 2 nm-node logic and DDR5. Due to these drivers, the WFE market is expected to show a double-digit growth.

For AI applications, cutting-edge semiconductor technologies are essential. Toward the realization of semiconductor devices featuring ultrahigh speed, large capacity, high reliability, and low power consumption, technology innovation is moving forward, supported by two primary drivers: the one is device scaling which is well-known intrinsic nature of semiconductor innovation and the other is a new driver, heterogeneous integration. Along with the evolution of such technologies as GAA, backside PDN, next-generation DRAM, higher-stacking NAND, and packaging processes, our business opportunities will expand more and more.

Strategic Technologies for Future Growth



Frontend		
Logic : GAA, BSPDN <ul style="list-style-type: none"> EUV Coater/Developer Gas Chemical Etch Conductor Etch PVD Metal Overburden CFET/Inner Spacer Plasma CVD for filling film Double-sided scrubber Backside/bevel cleaning Pattern Shaping Wafer Bonder Laser Tool 	DRAM: 2D & 3D DRAM <ul style="list-style-type: none"> EUV Coater/Developer Capacitor Mold Etch Batch High-k Capacitor deposition PVD Metal Hardmask Supercritical Cleaning Backside/bevel Cleaning Wafer Bonder Laser Tool 	NAND: Beyond 4xx <ul style="list-style-type: none"> Slit Etch Channel Hole Etch (Plug) Batch Mo deposition Batch Cleaning WL Separation Wafer Bonder Laser Tool
Advanced Packaging		
Logic Packaging <ul style="list-style-type: none"> Interposer, Polyimide & PR Coater/Developer TDV Etch Batch High-k Capacitor depo Wafer Bonder Laser Tool 	HBM Packaging <ul style="list-style-type: none"> Polyimide & PR Coater/Developer Metal Etch for HBM Aerosol Cleaning Temporary Bonder/Debonder 	Advanced Logic / Memory Test <ul style="list-style-type: none"> Prober

Together with our customers developing cutting-edge technologies, Tokyo Electron works on concurrent development of four generations, looking 10 years ahead. And this slide shows some examples of the focus technologies we are addressing for the next generation and the generation after. To capture these business opportunities for sure, we are actively investing in R&D so as to improve our future corporate value.

FY2026 Financial Estimates

Next, I will present the financial estimates for FY2026.

FY2026 Financial Estimates

(Billion Yen)

	FY2025 (Actual)	FY2026 (Estimates)			
		H1	H2	Full Year	Full Year YoY
Net sales	2,431.5	1,150.0	1,450.0	2,600.0	+6.9%
Gross profit	1,146.2	527.0	701.0	1,228.0	+7.1%
Gross profit margin	47.1%	45.8%	48.3%	47.2%	+0.1pts
SG&A expenses	448.9	239.0	262.0	501.0	+11.6%
R&D	250.0	140.0	160.0	300.0	+20.0%
Other than R&D	198.9	99.0	102.0	201.0	+1.1%
Operating income	697.3	288.0	439.0	727.0	+4.3%
Operating margin	28.7%	25.0%	30.3%	28.0%	-0.7pts
Income before income taxes	706.1	293.0	443.0	736.0	+4.2%
Net income attributable to owners of parent	544.1	224.0	342.0	566.0	+4.0%
Net income per share (Yen)	1,182.40	488.97	-	1,235.51	+53.11

Expect record high revenue and OP again in FY2026
Plan 300B yen R&D investment to maximize future growth opportunities

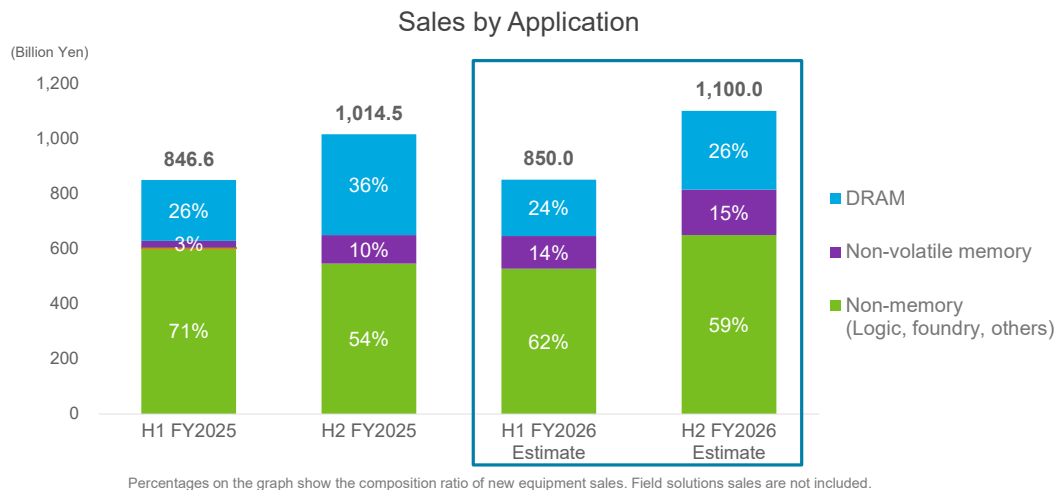
Investor Relations / April 30, 2025



17

In the on-going FY2026, we expect full-year net sales of 2 trillion 600 billion yen, positive growth of 6.9% year-over-year. The details are shown in this table. We expect record-high net sales and operating income again in this fiscal year. We will keep on investing for further growth, planning to invest 300 billion yen for R&D.

FY2026 SPE New Equipment Sales Forecast



Expect customers to begin preparations in H2 FY2026 in anticipation for market growth in CY2026.
Expect record-high half-year sales in H2 FY2026

This slide shows the SPE new equipment sales forecast.

As the investment in advanced nodes for AI server and the investment by Chinese chipmakers were pulled forward in the second half of FY2025, there is a sense of a lull in the first half of FY2026, but in the second half, we expect the situation will improve and the investment by customers preparing for CY2026 market growth will be activated. Based on this forecast, the SPE new equipment sales in the second half of this fiscal year are expected to be 1 trillion 100 billion yen, which is record high half-year sales.

FY2026 R&D Expenses and Capex Plan

New Development Building
Etch system



Kurokawa-gun, Miyagi Prefecture
Established in April 2025

New Development Building

Coater/developer, cleaning system, bonder



Koshi-city, Kumamoto Prefecture
Completion scheduled for autumn 2025

Tohoku Production and Logistics Center
Deposition system

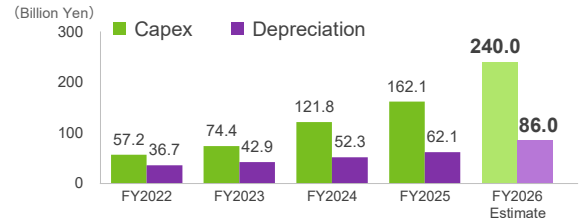
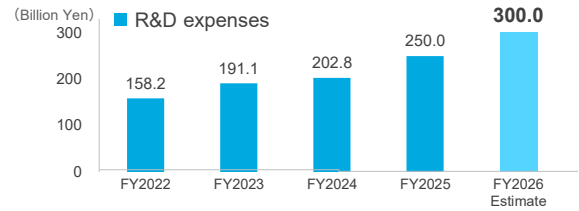


Oshu-city, Iwate Prefecture
Completion scheduled for autumn 2025

New Production Building
Etch system



Kurokawa-gun, Miyagi Prefecture
Completion scheduled for summer 2027

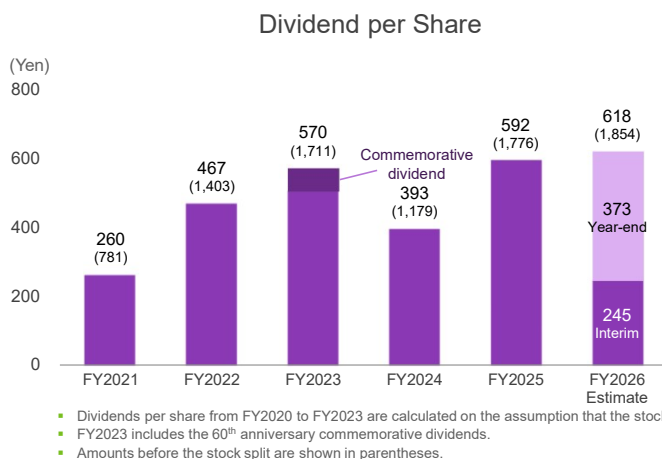


Continue aggressive R&D and capital investments for future growth

This shows our plan for R&D expenses and capex.

Following a new development building in Miyagi whose construction was completed the other day, construction of a new development building in Kumamoto and a production and logistics center in Iwate is planned to be completed in this fiscal year. In Miyagi, we will start construction of a new production building in June, which adopts next-generation smart manufacturing concept. In FY2026, we expect R&D expenses of 300 billion yen, capex of 240 billion yen, and depreciation of 86 billion yen.

FY2026 Dividend Forecast



TEL shareholder return policy

Dividend payout ratio: 50%

Annual DPS of not less than 50 yen*

We will review our dividend policy if the company does not generate net income for two consecutive fiscal years

We will flexibly consider share buybacks

*Due to the stock split on April 1, 2023, the amount has been changed from 150 yen to 50 yen.

Implemented a 3-for-1 common stock split on April 1, 2023.
Full-year dividends are expected to be 618 yen per share

This is my last slide showing the dividend forecast.

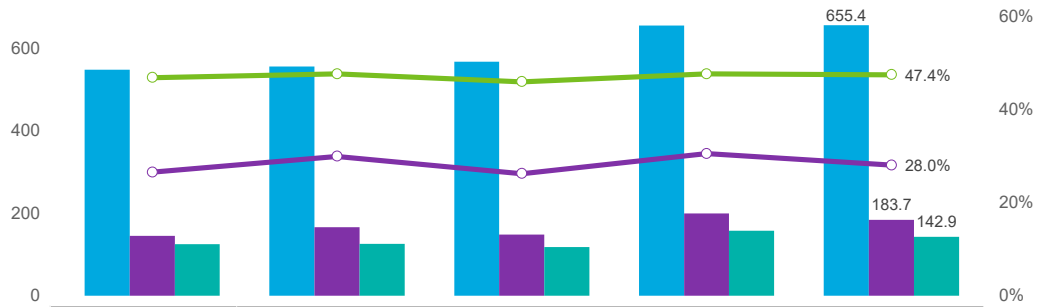
In FY2026, the full-year dividend per share is expected to be 618 yen, surpassing the previous record.

This concludes my presentation. Thank you very much for your kind attention.

Appendix

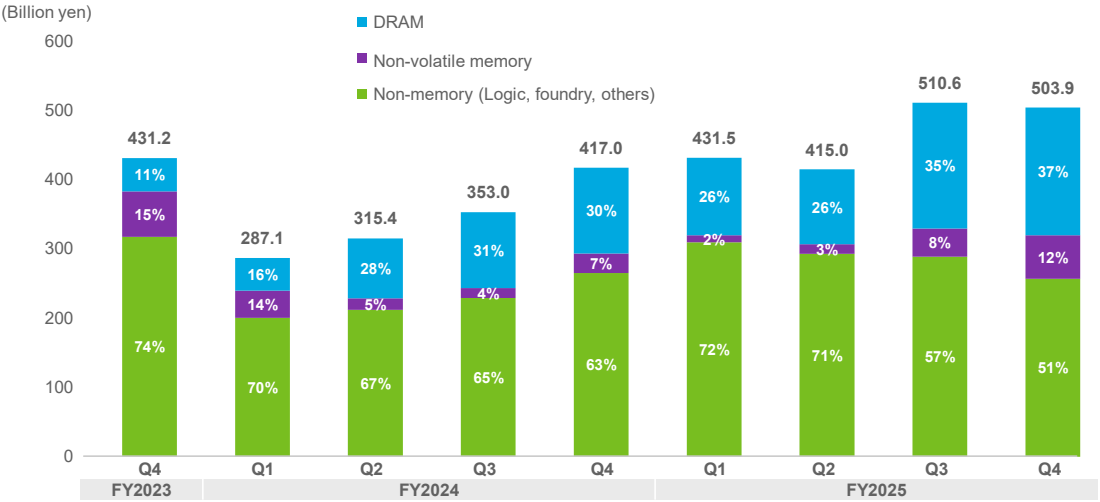
Financial Performance (Quarterly)

(Billion Yen)



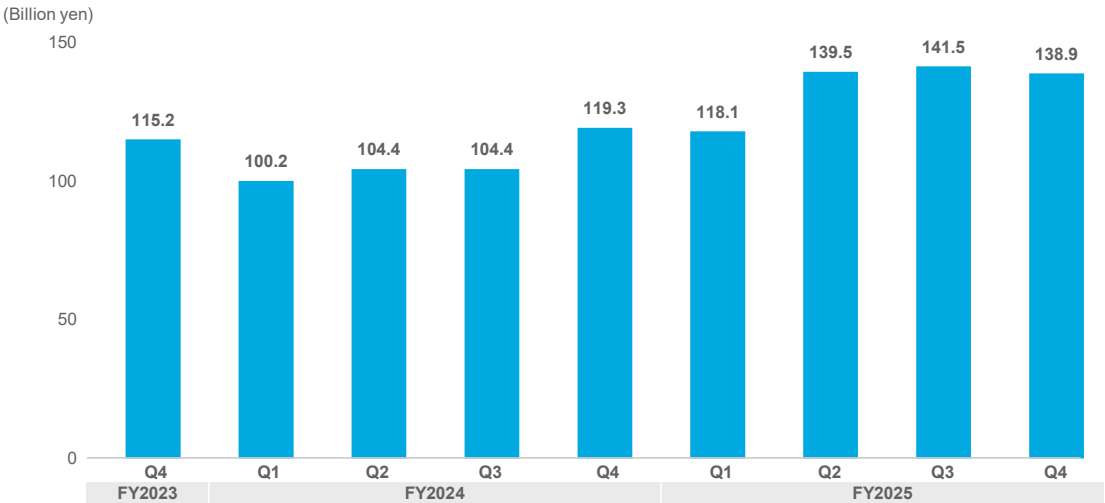
	FY2024	FY2025			
	Q4	Q1	Q2	Q4	Q4
Net sales	547.2	555.0	566.5	654.5	655.4
Operating income	145.2	165.7	148.1	199.6	183.7
Net income attributable to owners of parent	124.9	126.1	117.7	157.2	142.9
Gross profit margin	46.8%	47.6%	45.9%	47.6%	47.4%
Operating margin	26.5%	29.9%	26.2%	30.5%	28.0%

SPE New Equipment Sales by Application (Quarterly)

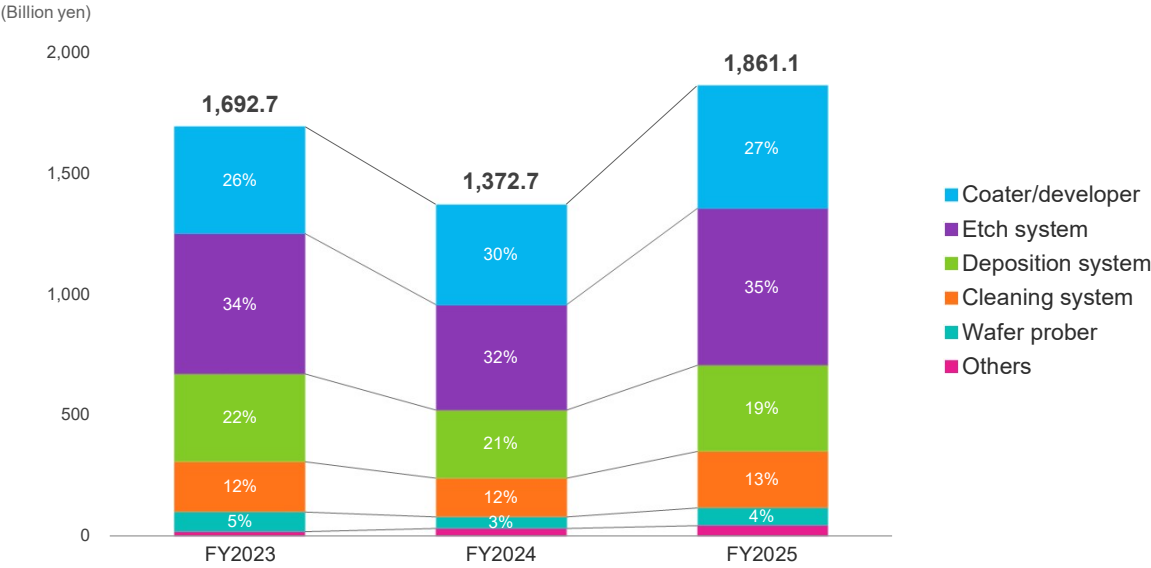


1. SPE: Semiconductor Production Equipment
2. Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.

Field Solutions Sales (Quarterly)

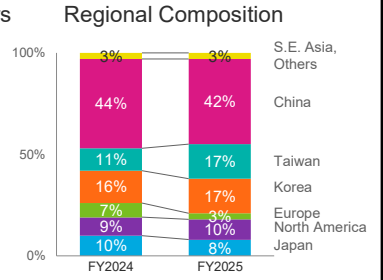
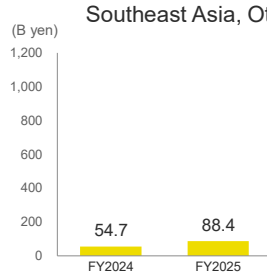
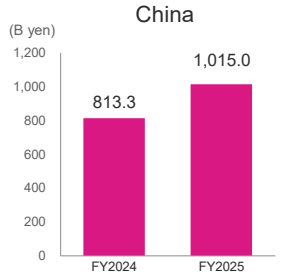
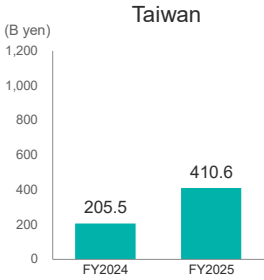
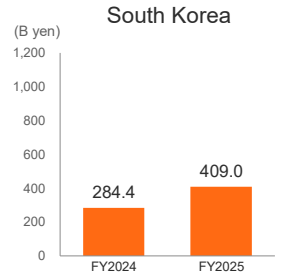
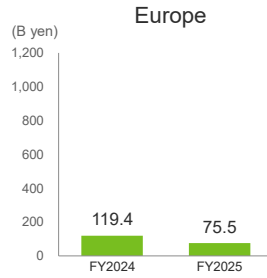
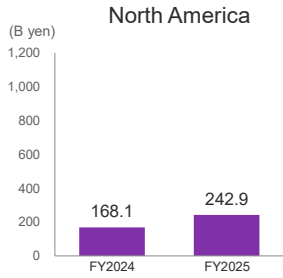
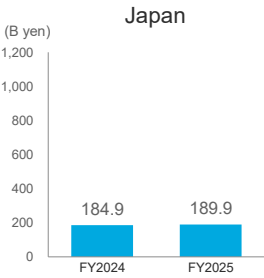


SPE New Equipment Sales by Product

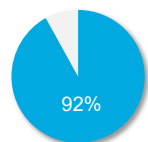


Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.

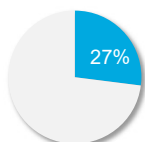
Sales by Region



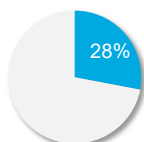
World Market Share of Major Products (CY2024)



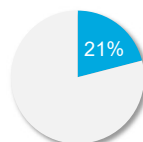
Coater/Developer



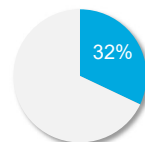
Dry Etch System



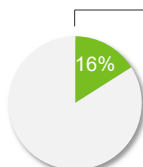
Deposition System



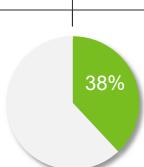
Cleaning System



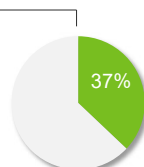
Wafer Bonder



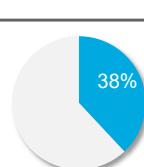
ALD



CVD



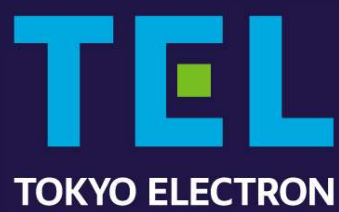
Oxidation/Diffusion



Wafer Prober

Source
SPE (excluding Wafer Prober) : Gartner®, Market Share: Semiconductor Wafer Fab Equipment, Worldwide, 2024, Bob Johnson and Menglin Cao, 21 April 2025, Revenue from Shipments basis. Chart created by TEL based on Gartner research. Gartner research. Calculations performed by TEL.
Coater/Developer: Photorealist Processing (Track); Dry Etch System: Dry Etch; Deposition System: Tube CVD + Atomic Layer Deposition Tools + Oxidation/Diffusion Furnaces + Nontube LPCVD; ALD: Atomic Layer Deposition Tools; CVD: Tube CVD + Nontube LPCVD; Oxidation/Diffusion: Oxidation/diffusion Furnaces; Cleaning System: Single Wafer Processors + Wet Stations + Batch Spray Processors + Scrubbers + Other Clean Equipment; Wafer Bonder: Wafer Bonder.
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Source
SPE (Wafer Prober) : Auto Probers, Technisights Inc., April 2025
Charts/graphics created by Tokyo Electron based on : Technisights Inc.



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